

Advanced Packaging Summit Agenda
April 18–19, 2024
Held at NASA Ames Conference Center

DAY 1		
8:00 – 9:00 am	Check-In	
9:00 – 9:20 am	Intro, Review Agenda, Expectations & logistics	Intro / NAPMP
9:20 – 9:25 am	Opening Remarks DoC	Laurie Locascio, DoC
9:25 – 9:30 am	Opening Remarks NASA	Eugene Tu, NASA
9:30 – 9:50 am	DARPA & National Strategy on Microelectronics Research	Carl McCants, DARPA
9:50 – 10:10 am	Natcast	Deirdre Hanford, Natcast
10:10 – 10:30 am	Break	Break
10:30 – 11:00 am	Semiconductor startup and investment landscape in 2024 ... the worst and best of times	Daniel Armbrust, Silicon Catalyst
11:00 – 11:30 am	NAPMP Overview	Daniel Berger, NAPMP
11:30 - 11:50 am	Chiplets	Bapi Vinnakota, NAPMP
11:50 – 1:00 pm	Lunch	Lunch
1:00 – 3:00 pm	Panel: Applications – HPC & AI	Panel Mod: John Shalf (DOE)
3:00 – 3:15 pm	Break	Break
3:15 – 4:30 pm	Panel: Applications – Aerospace & Automotive	Panel: Mod: Scott Bukofsky, NSTC
4:30 – 5:30 pm	Panel: Applications - Low Power	Panel Mod: George Orji, NAPMP
5:30 pm	Wrap up, Adjourn	George Orji, NAPMP

DAY 2		
8:30 – 9:00 am	Check-In (if needed)	
9:00 – 9:05 am	Intro, Review Agenda & Logistics	Intro / NAPMP
9:05 – 9:35 am	Semiconductors for the Future of Aerospace	Prasun Desai, NASA
9:35 – 10:05 am	Enabling Moore’s Law’s Through Heterogeneous Integration	Raja Swaminathan, AMD
10:05 – 10:20 am	Break	Break
10:20 – 11:30 am	Panel: Support for Startups	Panel Mod: Daniel Armbrust, Silicon Catalyst
11:30 – 12:30 pm	Lunch Break	Break
12:30 – 1:45 pm	Panel: Applications – Biomedical	Panel Mod: Andy DeHennis
1:45 – 3:00 pm	Panel: Packaging Pilot Needs & The Path to HVM	Panel Mod: Erik Hadland (SIA)
3:00– 3:15 pm	Break	Break
3:15 – 4:15 pm	Panel: Emerging Challenges to Advanced Packaging	Panel Mod: Matt Kelly (IPC)
20 mins	Advanced Packaging Acceleration	K.C. Hsu, TSMC
4:15 – 5:30 pm	Panel: Accelerating the Adoption of Advanced Packaging	Panel Mod: Bapi Vinnakota, NAPMP
5:30 pm	Closing Remarks, Adjourn	George Orji, NAPMP

Program Committee:

David LaVan (CHIPS)

Matt Kelly (IPC)

Bryan Biegel (NASA)

Matt Walsh (DoD – ReShape)

Bapi Vinnakota (CHIPS)

Erik Hadland (SIA)

Greg Yeric (CHIPS)

Andrew DeHennis (CHIPS)